

L	Hits	Search Text	DB	Time stamp
Number				
-	131	"5374564"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/25 14:32
-	131	"5374564"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/25 14:32
-	3	("4717683" "5196355" "5374564").PN.	USPAT	2002/07/25 14:38
-	42	5494835.URPN.	USPAT	2002/07/25 16:32
-	401	438/455.CCLS.	USPAT	2002/07/25 16:42
-	262	438/457-458.CCLS.	USPAT	2002/07/25 16:42
-	446	438/977.CCLS.	USPAT	2002/07/25 16:43
-	181	438/977.CCLS. and (substrate with (bond\$3 or laminat\$3))	USPAT	2002/07/25 16:44
-	0	438/977.CCLS. and (substrate with (bond\$3 or laminat\$3)) and (hydrogen with (implant\$3 or implantation))	USPAT	2002/07/25 16:45
-	16	438/977.CCLS. and (substrate with (bond\$3 or laminat\$3)) and (hydrogen with (implant\$3 or implantation))	USPAT	2002/07/25 16:46
-	75	438/455-458.CCLS. and (substrate with (bond\$3 or laminat\$3)) and (hydrogen with (implant\$3 or implantation))	USPAT	2002/07/25 16:50
-	76	438/455-458.CCLS. and (substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))	USPAT	2002/07/25 16:52
-	1	438/455-458.CCLS. and (substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation)) not (438/455-458.CCLS. and (substrate with (bond\$3 or laminat\$3)) and (hydrogen with (implant\$3 or implantation)))	USPAT	2002/07/25 16:51
-	32	438/459.CCLS. and (substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))	USPAT	2002/07/25 16:54
-	10	438/459.CCLS. and (substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation)) not (438/455-458.CCLS. and (substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation)))	USPAT	2002/07/25 16:52
-	3	438/464.CCLS. and (substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))	USPAT	2002/07/25 16:54
-	6	438/766.CCLS. and (substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))	USPAT	2002/07/25 16:55
-	15	(438/766, 479, 517, 976, "978").CCLS. and (substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))	USPAT	2002/07/25 16:56

273	(substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation)))	USPAT	2002/07/25 17:12
182	((substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))) and (glass\$2 or quartz)	USPAT	2002/07/25 16:57
97	((substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))) and (glass\$2 and quartz)	USPAT	2002/07/25 17:11
70	((substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))) and (glass\$2 near4 quartz)	USPAT	2002/07/25 16:59
0	jp2000315822\$3	USPAT	2002/07/25 17:15
0	jp2000-315822\$3	USPAT	2002/07/25 17:11
0	jp-2000315822\$3	USPAT	2002/07/25 17:11
0	2000315822\$3	USPAT	2002/07/25 17:11
0	2000-315822\$3	USPAT	2002/07/25 17:11
1	jp2000315822\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:16
0	jp2000-315822\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:16
2	2000-315822\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:17
104	((substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))) and (glass\$2 near4 quartz)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:18
34	((substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))) and (glass\$2 near4 quartz) not (((substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))) and (glass\$2 near4 quartz))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:18
421	(substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:19